Materials Declaration

Package	PBGA
Body Size	19 X 19
Ball Count	260
Option	SnPbAg
Ball Size	0.6mm

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica	71.0	3.07 E-01	257841
Resin	25.0	1.08 E-01	90789
Antimony oxide	2.5	1.08 E-02	9079
Carbon Black	1.5	6.49 E-03	5447

Laminate

Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	25.0	1.14 E-01	95688
Glass Fiber	25.0	1.14 E-01	95688
Copper	19.0	8.66 E-02	72723
Solder Mask	12.2	5.56 E-02	46696
Nickel	11.0	5.02 E-02	42103
Gold	7.8	3.56 E-02	29855

Solder Ball

Item	% of Solder ball	Weight (g)	PPM
Sn	62.0	1.53 E-01	128593
Pb	36.0	8.90 E-02	74667
Ag	2.0	4.94 E-03	4148

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	100.0	8.51 E-03	7143

Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	3.38 E-02	28377

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70.0	9.31 E-03	7815
Resin	20.0	2.66 E-03	2233
Silane	5.0	6.65 E-04	558
Amine	5.0	6.65 E-04	558

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA #3052
Cd	Not Detected	US EPA #3052
Hg	Not Detected	US EPA #3052
Cr+6	Not Detected	US EPA #7196A and #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	US EPA #3052
Cd	Not Detected	US EPA #3052
Hg	Not Detected	US EPA #3052
Cr+6	Not Detected	US EPA #7196A and #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Laminate

Item	PPM	Method
Pb	<2	SGS Test Report
Cd	<2	SGS Test Report
Hg	<2	SGS Test Report
Cr+6	Not Detected	SGS Test Report
PBB	Not Detected	SGS Test Report
PBDE	Not Detected	SGS Test Report

Package Totals

Weight (g)	PPM
1.19 E+00	1000000

STS-B-C

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information

ANALOG DEVICES

ADI Proprietary

3/22/06